















































































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PD03			PD03				
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PE00			PE00				
PE02			PE02				
PE03			PE03				
PB06			PB06				
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PC09			PC09				
PF06			PF06				
PA08			PA08				
PA10			PA10				
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PB05			PB05				
PB04			PB04				

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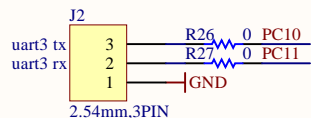
Date: 2019/5/28 Sheet 1 of 4

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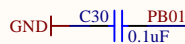
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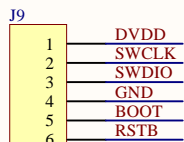


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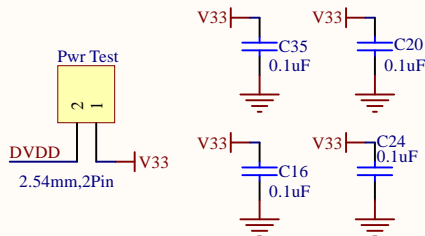
▲PB01引脚外接电容
以减少ADC输入信号噪声

Analog CAP

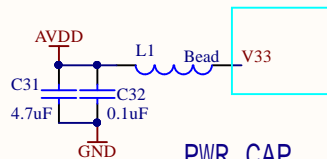


2.54mm,6Pin

SWD

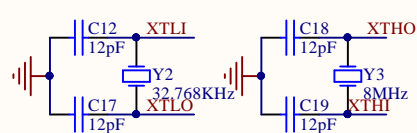


DVDD
2.54mm,2Pin

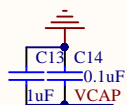


PWR CAP

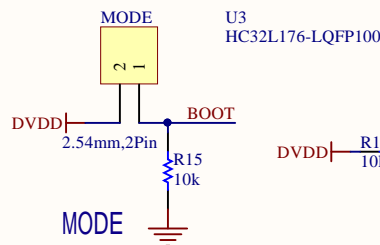
▲模拟部分，电源用磁珠隔离，地不做分割！



XTAL



VCAP

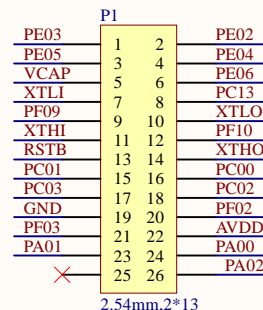


MODE

RST

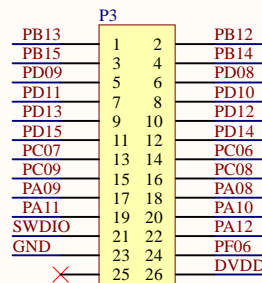
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PE06	5	PE06	PB09	96	PB09
VCAP	6	VCAP	PB08	95	PB08
PC13	7	PC13	BOOT/PF11	94	BOOT
XTLI	8	PC14/xtli	PB07/i2c0_sda	93	PB07
XTLO	9	PC15/xtlo	PB06/i2c0_scl	92	PB06
PF09	10	PF09	PB05	91	PB05
PF10	11	PF10	PB04	90	PB04
XTHI	12	PF00/xthi	PB03	89	PB03
XTHO	13	PF01/xtho	PD07	88	PD07
RSTB	14	NRST	PD06	87	PD06
PC00	15	PC00	PD05/can_stb	86	PD05
PC01	16	PC01	PD04	85	PD04
PC02	17	PC02	PD03	84	PD03
PC03	18	PC03	PD02	83	PD02
PF02	19	PF02	PD01/can_tx	82	PD01
GND	20	AVSS	PD00/can_rx	81	PD00
AVDD	21	AVDD	PC12	80	PC12
PF03	22	PF03	PC11/uart3_rxd	79	PC11
PA00	23	PA00	PC10/uart3_txd	78	PC10
PA01	24	PA01	PA15	77	PA15
PA02	25	PA02	swclk/PA14	76	SWCLK
PA03	26	PA03	USBVDD	75	USBVDD
GND	27	DVSS	USBVSS	74	GND
V33	28	DVDD	PF06	73	PF06
PA04	29	PA04	swdio/PA13	72	SWDIO
PA05	30	PA05/dac1_out	PA12/d+	71	PA12
PA06	31	PA06	PA11/d-	70	PA11
PA07	32	PA07	PA10	69	PA10
PC04	33	PC04	PA09	68	PA09
PC05	34	PC05/adc15_in	PA08	67	PA08
PB00	35	PB00	PC09/i2s1_ws	66	PC09
PB01	36	PB01/ERef	PC08/i2s1_sd	65	PC08
PB02	37	PB02	PC07/i2s1_mck	64	PC07
PE07	38	PE07	PC06/i2s1_sck	63	PC06
PE08	39	PE08	PD15	62	PD15
PE09	40	PE09	PD14	61	PD14
PE10	41	PE10	PD13	60	PD13
PE11	42	PE11	PD12	59	PD12
PE12	43	PE12	PD11/i2s0_ws	58	PD11
PE13	44	PE13	PD10/i2s0_sd	57	PD10
PE14	45	PE14	PD09/i2s0_mck	56	PD09
PE15	46	PE15	PD08/i2s0_sck	55	PD08
PB10	47	PB10/scl	PB15/spi1_mosi	54	PB15
PB11	48	PB11/sda	PB14/spi1_miso	53	PB14
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U3
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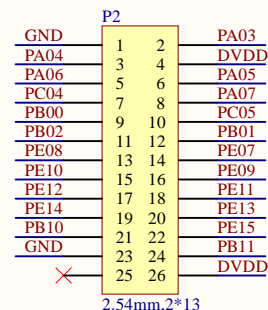


2.54mm,2*13

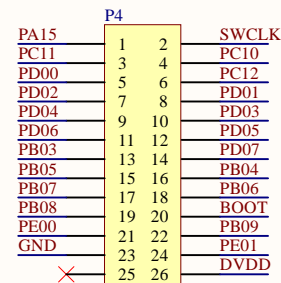
EXT_I/O I/F



2.54mm,2*13



2.54mm,2*13



2.54mm,2*13

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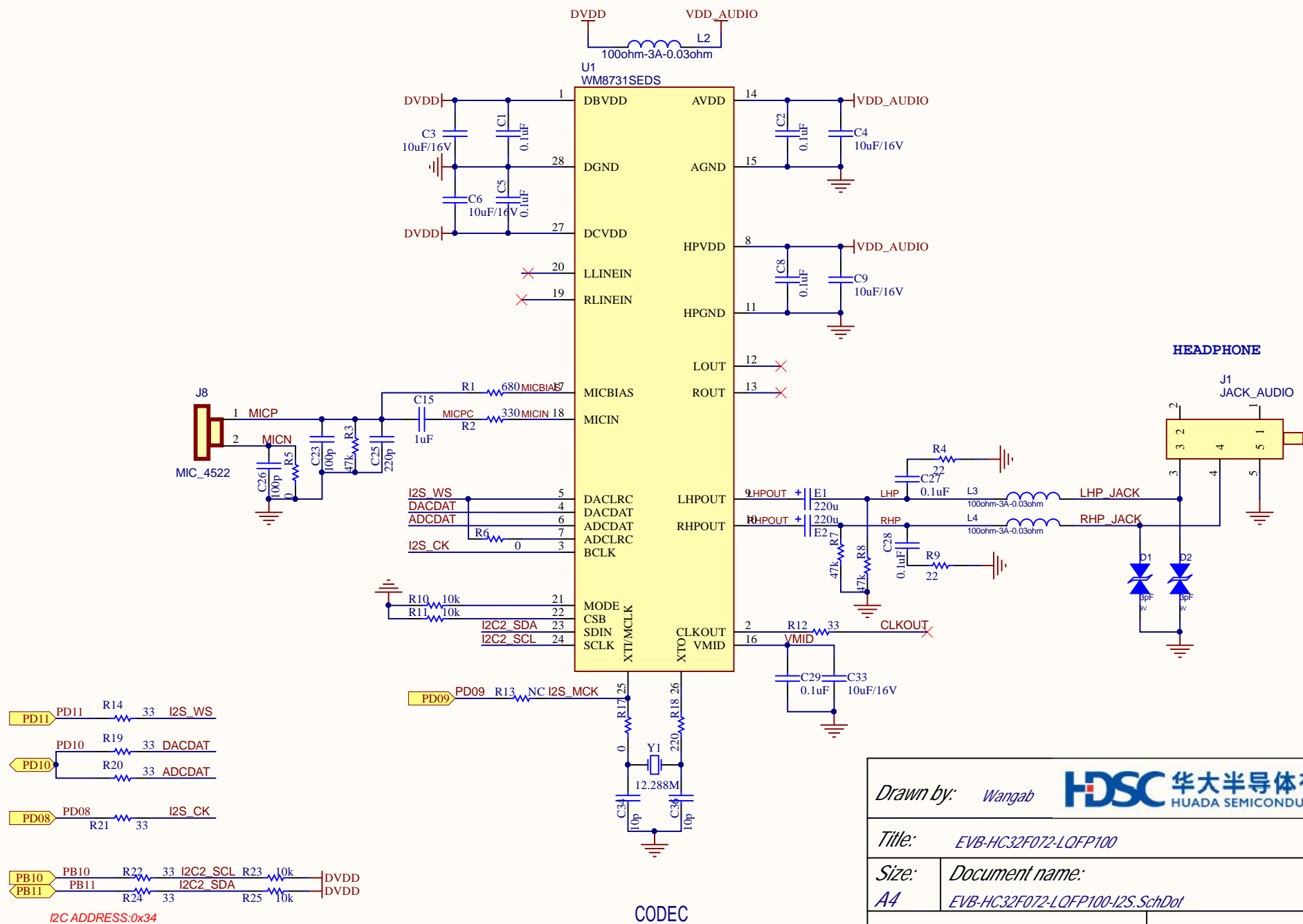
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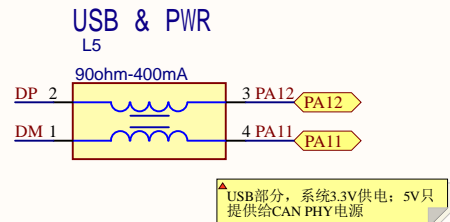
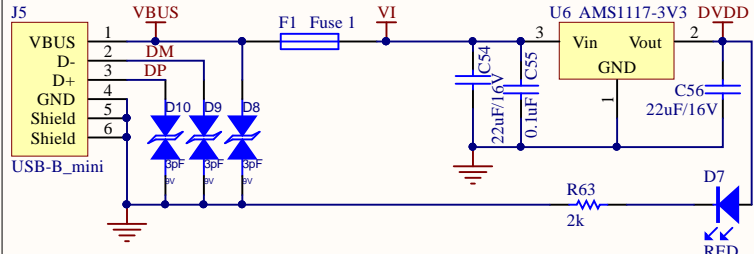
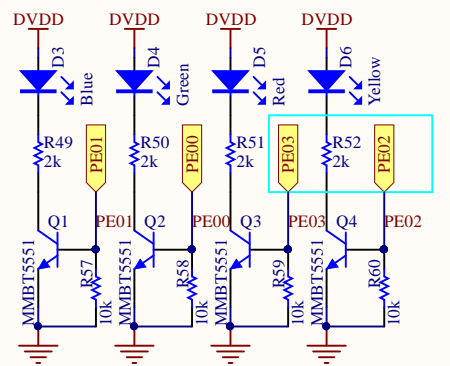
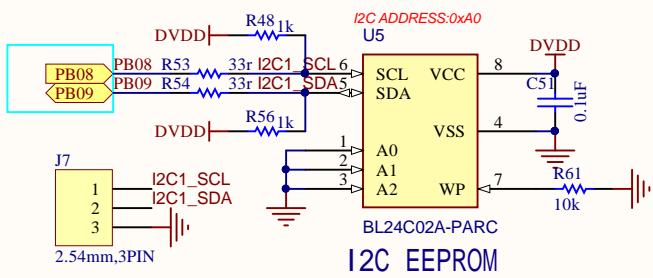
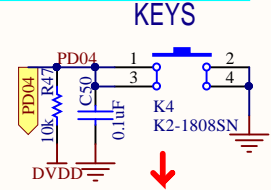
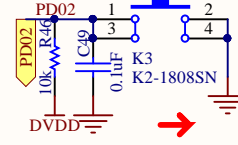
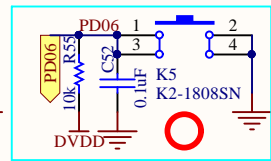
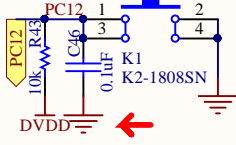
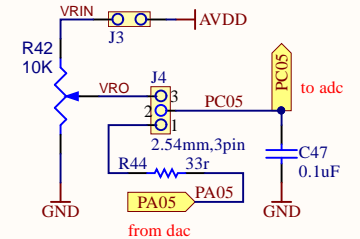
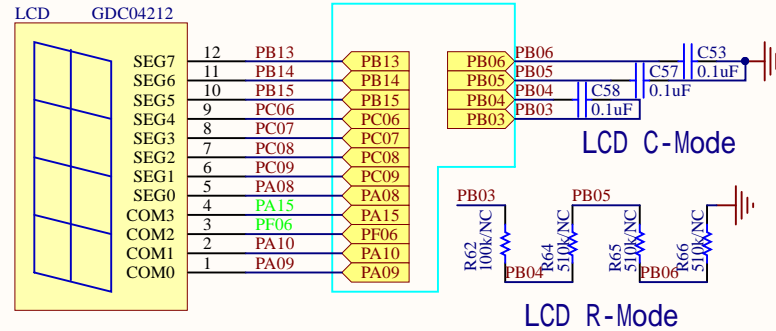
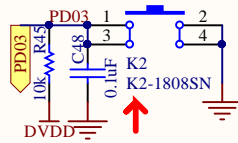
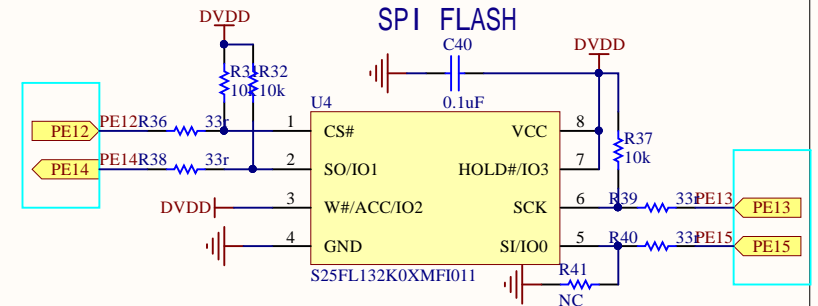
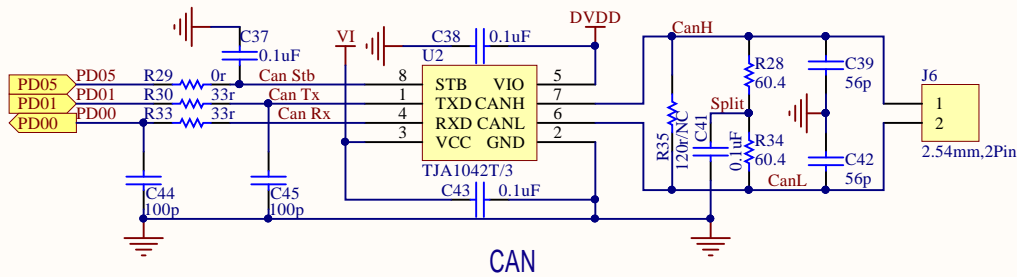
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Date: 2019/6/20

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